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AMENDMENTS TO THE CLAIMS

1. (Currently amended) A peroxide curable silicon adhesive composition comprising 20 to 80 parts by weight of a diorganopolysiloxane (A), represented by any one of the following formulae,

 $\underline{R^2_3SiO-(R^2_2SiO)_p-SiR^2_3}$

 R^2 ₂(HO)SiO-(R^2 ₂SiO)_p-Si R^2 ₂(OH)

wherein R² may be the same with or different from each other and is a hydrocarbon group having 1 to 10 carbon atoms, and p is such a number that a viscosity at 25 °C of component (A) is 500 mPa·s or higher,

80 to 20 parts by weight of a polyorganosiloxane (B) comprising R¹₃SiO_{0.5} unit and SiO₂ unit in a molar ratio of the R¹₃SiO_{0.5} unit to the SiO₂ unit of from 0.6 to 1.7, wherein R¹ is a monovalent hydrocarbon group having 1 to 10 carbon atoms,

0.01 to 1.0 part by weight, based on a total of (A) and (B) of 100 parts by weight, of a hindered amine moiety (C) having the molecular structure represented by the following formula,

$$\begin{array}{c}
R \\
R \\
N-\\
R
\end{array}$$

wherein R is a monovalent hydrocarbon group having 1 to 6 carbon atoms, and

0.1 to 5.0 parts by weight, based on a total of (A) and (B) of 100 parts by weight, of an organic peroxide (D).

- 2. (Original) The peroxide curable silicon adhesive composition according to claim 1, wherein the diorganopolysiloxane (A) comprises 1 to 35 mole % of diphenylsiloxy unit.
- 3. (Currently Amended) An addition-reactive silicon adhesive composition comprising

20 to 80 parts by weight of a diorganopolysiloxane (A') having 2 or more alkenyl groups and a viscosity of at least 1,000 mPa·s in the case that the diorganopolysiloxane (A') is oily at 25 °C, or at most 100,000 mPa·s in a 30 wt% solution in toluene in the case that the diorganopolysiloxane (A') is gummy at 25 °C,

80 to 20 parts by weight of a polyorganosiloxane (B) comprising $R^1_3SiO_{0.5}$ unit and SiO_2 unit in a molar ratio of the $R^1_3SiO_{0.5}$ unit to the SiO_2 unit of from 0.6 to 1.7, wherein R^1 is a monovalent hydrocarbon group having 1 to 10 carbon atoms,

0.01 to 1.0 part by weight, based on a total of (A') and (B) of 100 parts by weight, of a hindered amine moiety (C) having the molecular structure represented by the following formula,

$$R$$
 R
 $N R$
 R

a polyorganosiloxane (E)having SiH group in such an amount that a molar ratio of the SiH group to the alkenyl group of the component(A') ranges from 0.5 to 20,

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0 to 8.0 part by weight, based on a total of (A') and (B) of 100 parts by weight, of a retarder (F), and

a platinum catalyst (G) in such an amount that an amount as platinum ranges from 1 to 5000 ppm based on a total of (A') and (B) of 100 parts by weight.

- 4. (Original) The addition-reactive silicon adhesive according to claim 3, wherein the diorganopolysiloxane (A') comprises 1 to 35 mole % of diphenylsiloxy unit.
- 5. (Original) The addition-reactive silicon adhesive according to claim 3, wherein the composition further comprises 0.1 to 10 parts by weight, based on a total of (A') and (B) of 100 parts by weight, of a phenolic antioxidant (H).
- 6. (Original) An adhesive tape comprising a plastic film and an adhesive applied on at least one side of the plastic film, the adhesive being made by curing the adhesive composition according to claim 1 or 3.
- 7. (New) The peroxide curable silicon adhesive composition according to claim 1, wherein the diorganopolysiloxane (A) has a viscosity at 25 °C of 10,000 mPa·s or higher.
- 8. (New) The peroxide curable silicon adhesive composition according to claim 1, wherein the polyorganosiloxane (B) has an OH group in an amount of 4.0 wt % or smaller based on a total weight of the polyorganosiloxane (B).

9. (New) The addition-reactive silicon adhesive composition according to claim 3, wherein the polyorganosiloxane (B) has an OH group in an amount of 4.0 wt % or smaller based on a total weight of the polyorganosiloxane (B).

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10. (New) The peroxide curable silicon adhesive composition according to claim 1, wherein the hindered amine moiety (C) is at least one compound selected from the group consisting of

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11. (New) The addition-reactive silicon adhesive composition according to claim 3, wherein the hindered amine moiety (C) is at least one compound selected from the group consisting of

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- 12. (New) The peroxide curable silicon adhesive composition according to claim 1, wherein no residue is left when the adhesive composition is heated up to 280 °C.
- 13. (New) The addition-reactive silicon adhesive composition according to claim 3, wherein no residue is left when the adhesive composition is heated up to 280 °C.